



BSI Standards Publication

Semiconductor devices — Mechanical and climatic test methods

Part 44: Neutron beam irradiated single
event effect (SEE) test method for
semiconductor devices

National foreword

This British Standard is the UK implementation of EN 60749-44:2016. It is identical to IEC 60749-44:2016.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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**Semiconductor devices - Mechanical and climatic test methods -
Part 44: Neutron beam irradiated single event effect (SEE) test
method for semiconductor devices
(IEC 60749-44:2016)**

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 44: Méthode d'essai des
effets d'un événement isolé (SEE) irradié par un faisceau
de neutrons pour des dispositifs à semiconducteurs
(IEC 60749-44:2016)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 44: Prüfverfahren zur Einzelereignis-
Effekt-Neutronenbestrahlung von Halbleiterbauelementen
(IEC 60749-44:2016)

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In the official version, for Bibliography, the following note has to be added for the standard indicated :

IEC 60749-38 NOTE Harmonized as EN 60749-38.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 44: Neutron beam irradiated single event effect (SEE) test method for semiconductor devices

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